



## DATA SHEET NexSil™ SP-521K

### NexSil™ SP-521K GERMANIUM POLISHING SLURRY

#### PRODUCT DESCRIPTION

NexSil SP-521K is developmental polishing slurry for Germanium wafer polishing. The product is supplied at pH 9-10 and 30% solids.

Polishing of Germanium wafers using NexSil SP-521K should be done at 3-4 psi on the wafer surface and at a 25° C temperature. Slurry flow will depend on the pad and process conditions being used. The slurry should be used at the concentration supplied. Typical removal rates are 0.4 to 0.5 microns per minute at 3.7 psi using a Suba™ 1200 pad.

#### TYPICAL PROPERTIES

Appearance:	Translucent Slurry
Solids, %:	30
pH:	9 - 10
Particle Size, nm, by Malvern HPPS:	110 - 135

#### PACKAGING

NexSil SP-521K polishing slurry is available in 5-gallon pails and 55-gallon drums.

#### STORAGE

NexSil SP-521K polishing slurry should be stored above 32°F to protect from freezing.

#### SAFETY

NexSil SP-521K polishing slurry is mildly alkaline and may cause eye and skin irritation. Observe precautions printed on the package label. A Safety Data Sheet will be supplied on request.

#### FOR ADDITIONAL INFORMATION OR TO ORDER MATERIAL

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